**Introduction to Semiconductors and Packaging Course Schedule**

**Class start time: IST 7:30 PM**

**Class Duration: 2.5 Hours (2 hours lecture time & 30 minutes for Q&As)**

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| **Module No.** | **Date** | **Module Name** | **Speaker** |
| 1 | September 23 | Introduction to Semiconductors and Packaging | Prof. Rao R. Tummala, Georgia Tech |
| 2 | September 24 | Introduction to Devices | Prof. Abhisek Dixit, IIT Delhi |
| 3 | September 30 | Fundamentals of Electrical Design | Prof. Madhavan Swaminathan, Penn State |
| 4 | October 1 | Fundamentals of Thermal Technologies | Prof. Anandaroop Bhattacharya, IIT Kharagpur |
| 5 | October 7 | Fundamentals of Thermo-mechanical Reliability | Prof. Ganesh Subbarayan,  Purdue University |
| 6 | October 8 | Fundamentals of Package Materials | Dr. Ravi Bhatkal, MacDermid Alpha India |
| 7 | October 14 | Fundamentals of Substrates | Dr. Venky Sundaram, 3D System Scaling LLC |
| 8 | October 15 | Fundamentals of Passive Components and Their Integration | Prof. Raj Pulugurtha, Florida International University |
| 9 | October 28 | Fundamentals of Chip-to-Package Interconnect. & Assembly | Prof. Vanessa Smet, Georgia Tech |
| 10 | October 29 | Fundamentals of package encapsulation, molding, and sealing | Dr. Jack Moon, GT |
| 11 | November 4 | Fundamentals of 3D Packaging With and without TSV | Dr. Siddharth Ravichandran, Chipletz |
| 12 | November 5 | Fundamentals of Opto-electronics packaging | Dr. Ajey Jacobs, USC |
| 13 | November 18 | Fundamentals of RF and Mm wave packaging | Prof Manos Tentzeires, GT |
| 14 | November 19 | Fundamentals of MEMS and Sensors packaging | Prof. Venkatesh KP Rao, BITS Pilani |
| 15 | November 25 | Fundamentals of Printed Wiring Boards | Dr. Sundar Kamath, Sanmina |
| 16 | November 26 | Fundamentals of Board Assembly | Prof. Nilesh Badwe, IIT Kanpur |
| 17 | December 2 | Fundamentals of Embedded & Fan Out Packaging | Dr. Beth Keser, Zero Asic |
| 18 | December 3 | Automotive electronics | Prof. Kaushik Basu, IISc |
| 19 | December 9 | Computing Systems | Dr. Ravi Mahajan, Intel |
| 20 | December 10 | Flexible Electronics | Prof. S. Sundar Kumar Iyer, IIT Kanpur |
| 21 | December 16 | Memory Packaging & Manufacturing | Dr. Gokul Kumar, Micron |